

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claims 1-8 (canceled)

1                   Claim 9. (original) A method of making a chip device, the method  
2 comprising:  
3                   providing a die;  
4                   providing a leadframe including a die attach cavity and a plurality of dimples  
5 defined around a periphery of the leadframe, the die attach cavity having substantially the  
6 same thickness as the die;  
7                   placing solder balls into the dimples; and  
8                   flipping the die into the die attach cavity and attaching it therein.

1                   Claim 10. (original) The method of claim 9 wherein the die provided is a  
2 bumped die.

1                   Claim 11. (new) The method of claim 9 wherein the die has solder balls  
2 thereon to serve as source and gate connections.

1                   Claim 12. (new) The method of claim 9 wherein the step of attaching the die  
2 is performed such that the die is coplanar with a top surface of the leadframe.

1                   Claim 13. (new) The method of claim 9 further comprising the step of adding  
2 a solderable coating to the leadframe.

1                   Claim 14. (new) The method of claim 9 wherein the leadframe is conductive.

1                   Claim 15. (new) The method of claim 14 wherein the conductive leadframe  
2 comprises a copper based alloy.